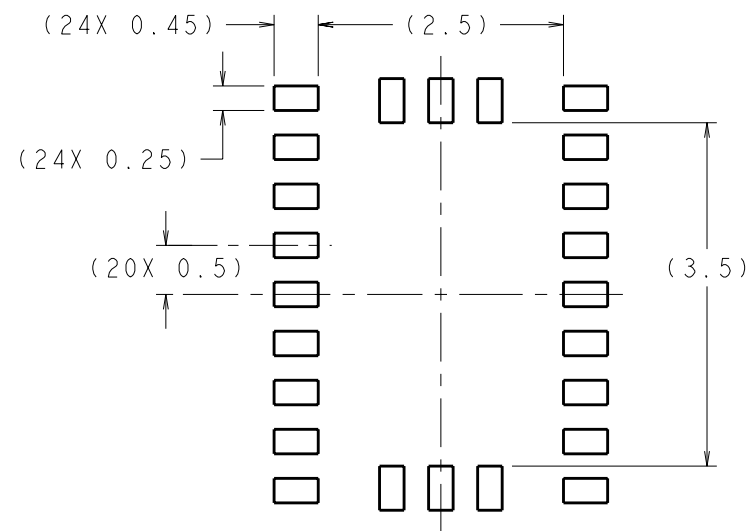
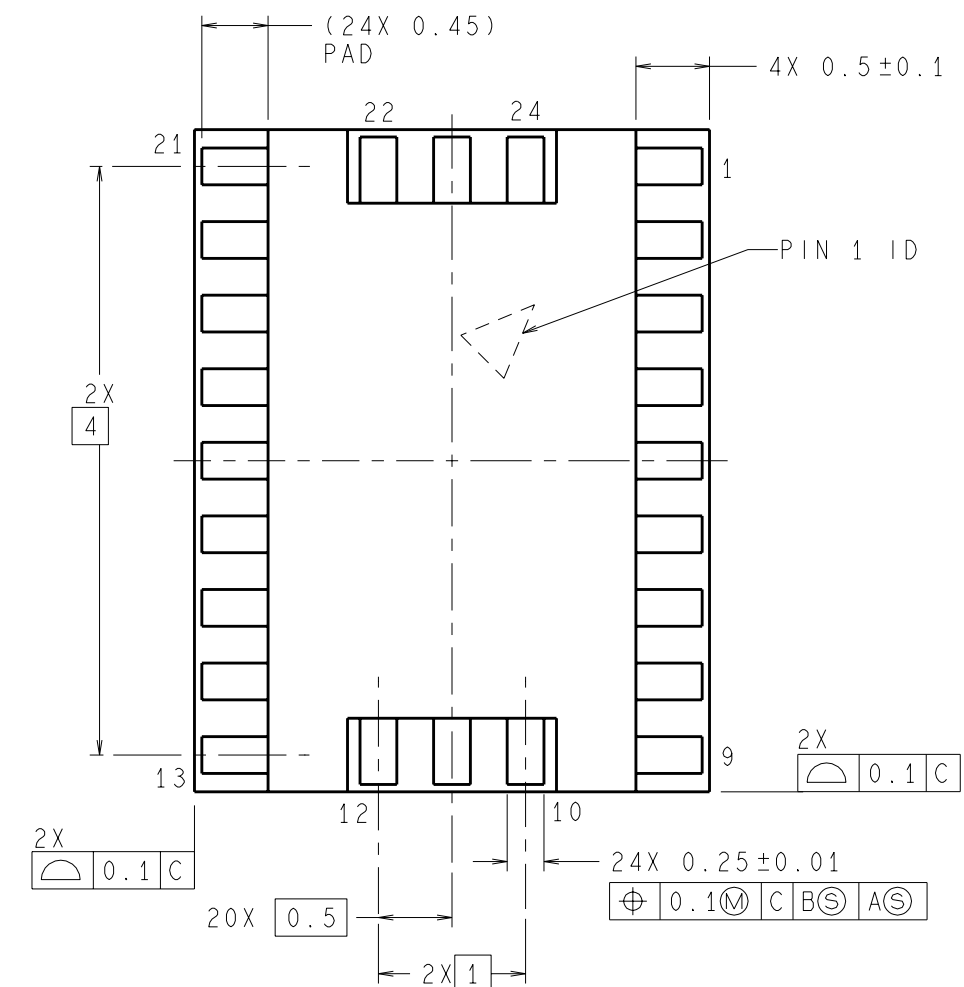
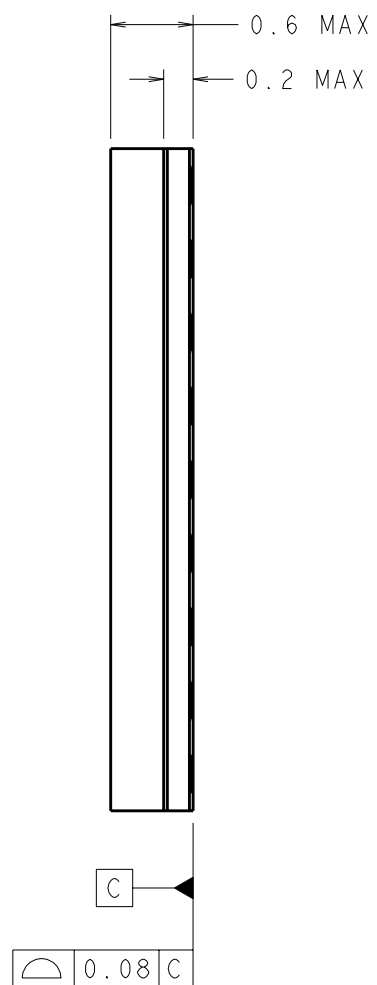
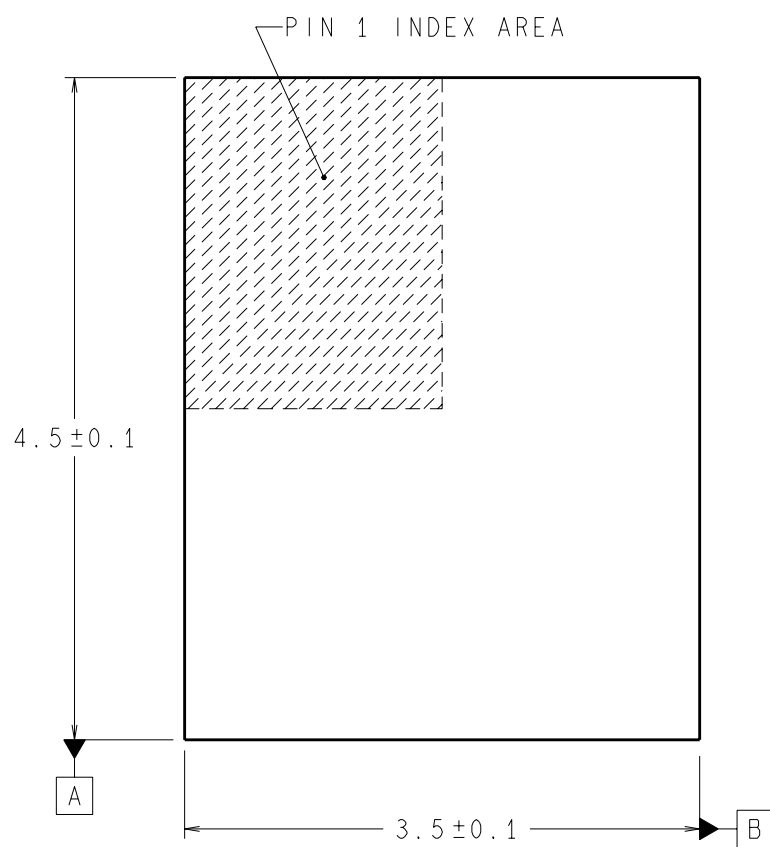


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
A	RELEASE TO DOCUMENT CONTROL	351	06/29/2001	TL/AT



DIMENSIONS ARE IN MILLIMETERS

RECOMMENDED LAND PATTERN
1:1 RATIO WITH PACKAGE SOLDER PADS



NOTES: UNLESS OTHERWISE SPECIFIED

- MATERIAL: BT RESIN CCL-HL832-H/S WITH TAIYO PSR4000 AUS5 SOLDER MASK.
- PLATING: Cu 15 TO 20 MICROMETERS (FULL)
Ni 10 ± 5 MICROMETERS (LEADS ONLY)
Au 0.75 ± 0.25 MICROMETER (LEADS ONLY)
- REFERENCE JEDEC REGISTRATION MO-208, VARIATION ECE-1.

APPROVALS	DATE	National Semiconductor			
DRAWN T. LEQUANG	06/29/2001	2900 Semiconductor Dr., Santa Clara, CA 95052-8090			
DFTG. CHK. MARTA SUCHY	06/29/2001	ULTRA THIN CSP, PLASTIC, LAMINATED, 3.5 X 4.5 X 0.6 mm BODY, 24 L, 0.5mm PITCH			
ENGR. CHK. ANNY TU	06/29/2001				
		SCALE N/A	SIZE C	DRAWING NUMBER (SC)MKT-SLE24A	REV A
		DO NOT SCALE DRAWING		SHEET 1 of 1	